

Supporting Information for

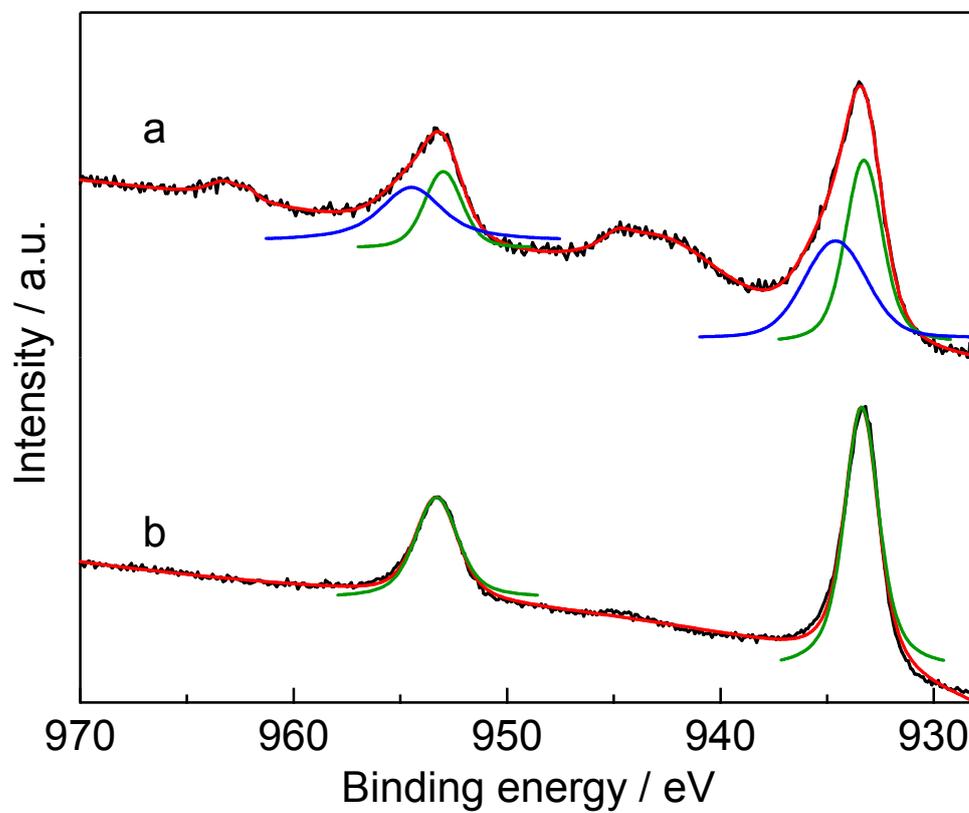
**Electrocatalytic Conversion of Carbon Dioxide to Formic  
Acid over Nanosized Cu<sub>6</sub>Sn<sub>5</sub> Intermetallic Compounds with a  
SnO<sub>2</sub> Shell Layer**

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Miyachi and Futoshi Matsumoto**

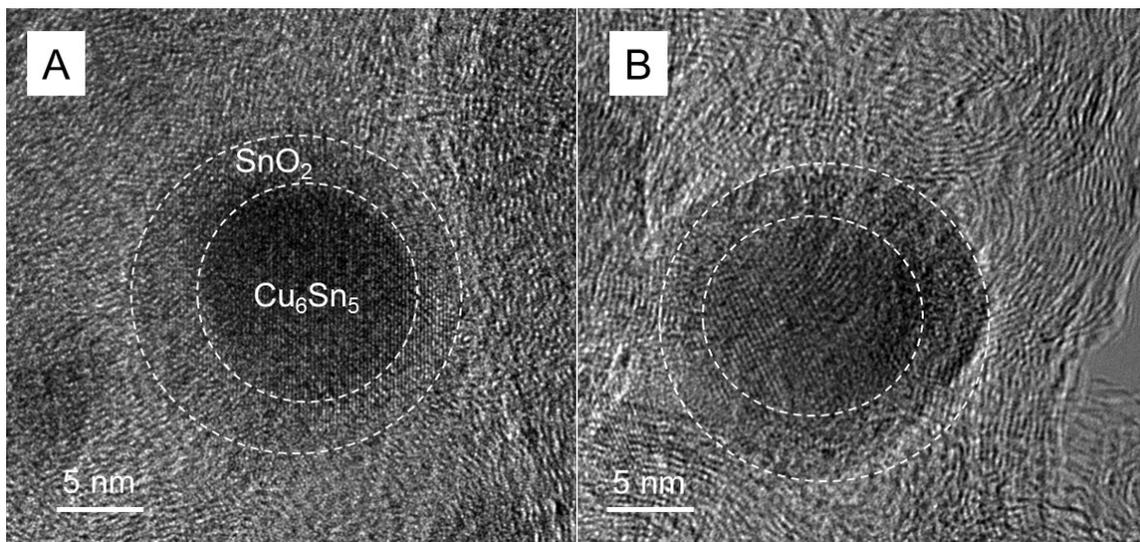
## Supporting Table and Figures

**Table S1** Summarized XPS analysis

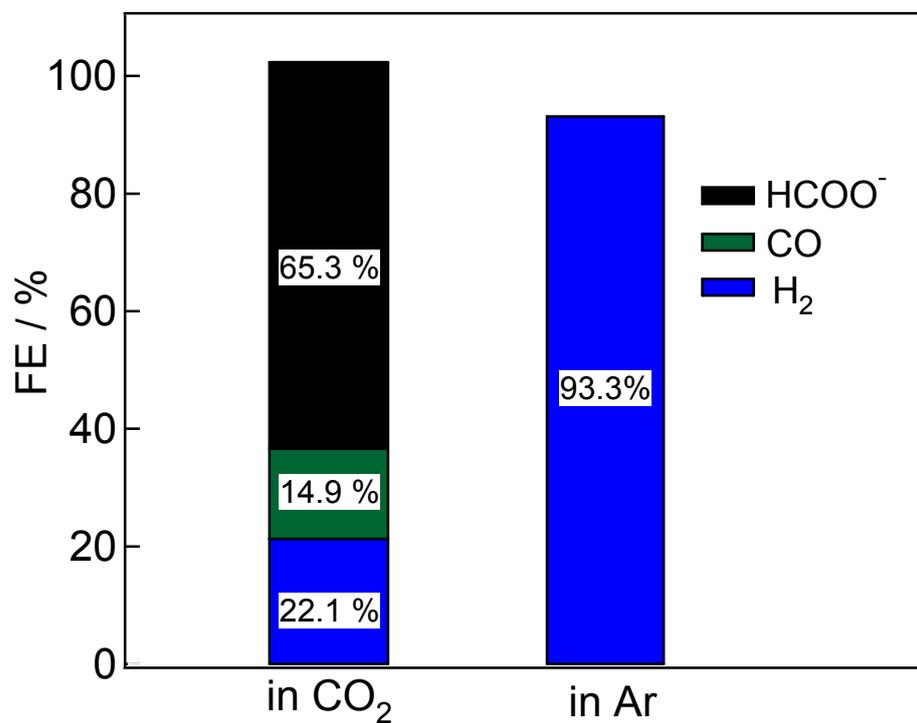
Entry	Sn (%)	Cu (%)
Cu <sub>6</sub> Sn <sub>5</sub> /CB (Without etching)	80.1	19.9
Cu <sub>6</sub> Sn <sub>5</sub> /CB (Etching time : 6s)	52.8	47.2
Cu <sub>6</sub> Sn <sub>5</sub> /CB (Etching time : 16s)	54.7	45.3



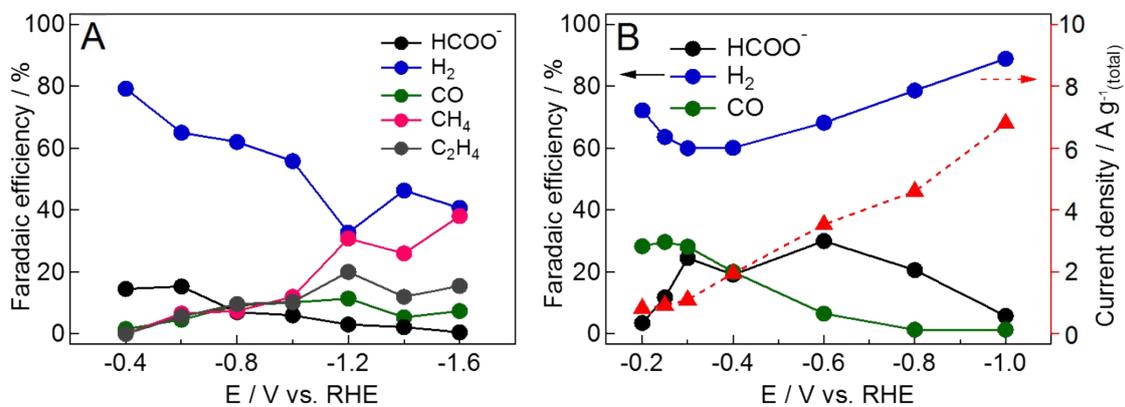
**Figure S1** XPS profile for Cu<sub>6</sub>Sn<sub>5</sub> NPs/CB in the Cu 2p region (a) before and (b) after 6s etching treatment.



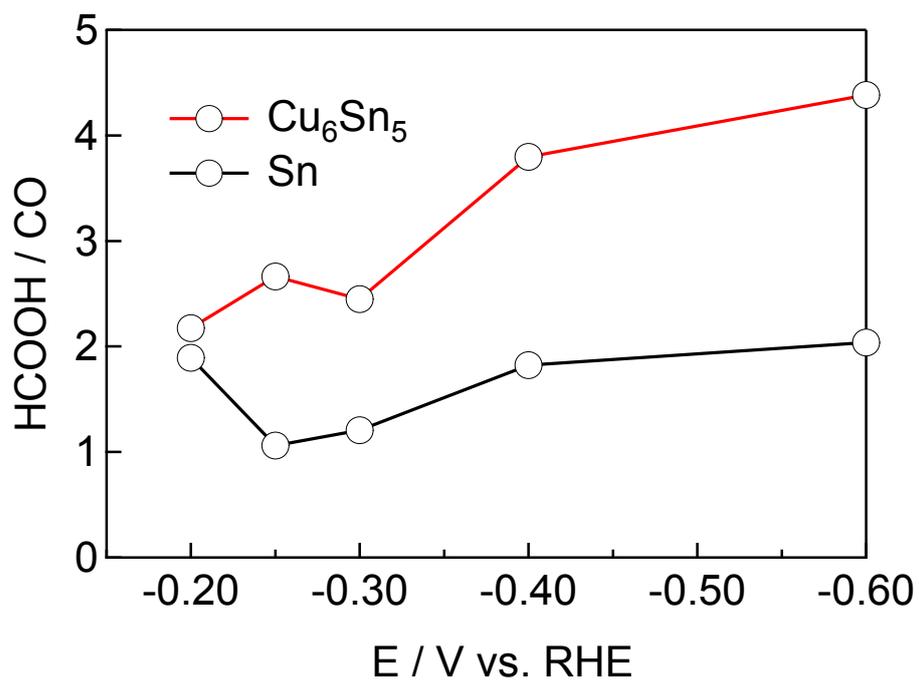
**Figure S2.** (A, B) High-magnification TEM images of  $\text{Cu}_6\text{Sn}_5$  NP/CB sample. These images were captured in different area.



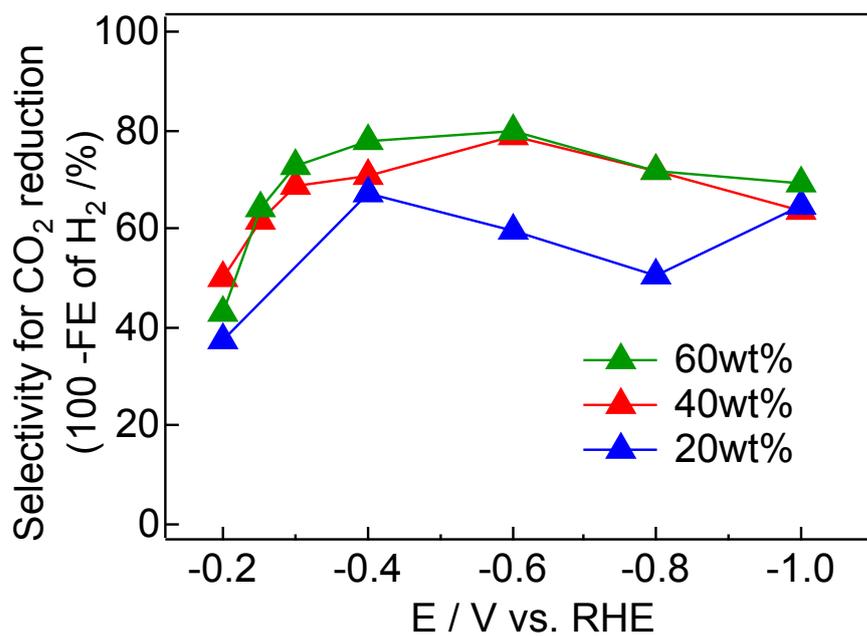
**Figure S3** Faradaic efficiencies for HCOO<sup>-</sup>, CO and H<sub>2</sub> produced over Cu<sub>6</sub>Sn<sub>5</sub> NP/CB at -0.6 V vs RHE in Ar- and CO<sub>2</sub>-saturated 0.1 M KHCO<sub>3</sub> aqueous solution.



**Figure S4** Potential dependence on Faradaic efficiency (left) and current density (right) towards electrochemical reduction of CO<sub>2</sub> over (A) Cu plate and (B) Cu NPs/CB.



**Figure S5** Potential dependence on production ratio over Sn NPs/CB and Cu<sub>6</sub>Sn<sub>5</sub> NPs/CB.



**Figure S6** Electrocatalytic selectivity (100 % - FE of H<sub>2</sub>) over Cu<sub>6</sub>Sn<sub>5</sub> NP/CB with various loading weight % of metal.

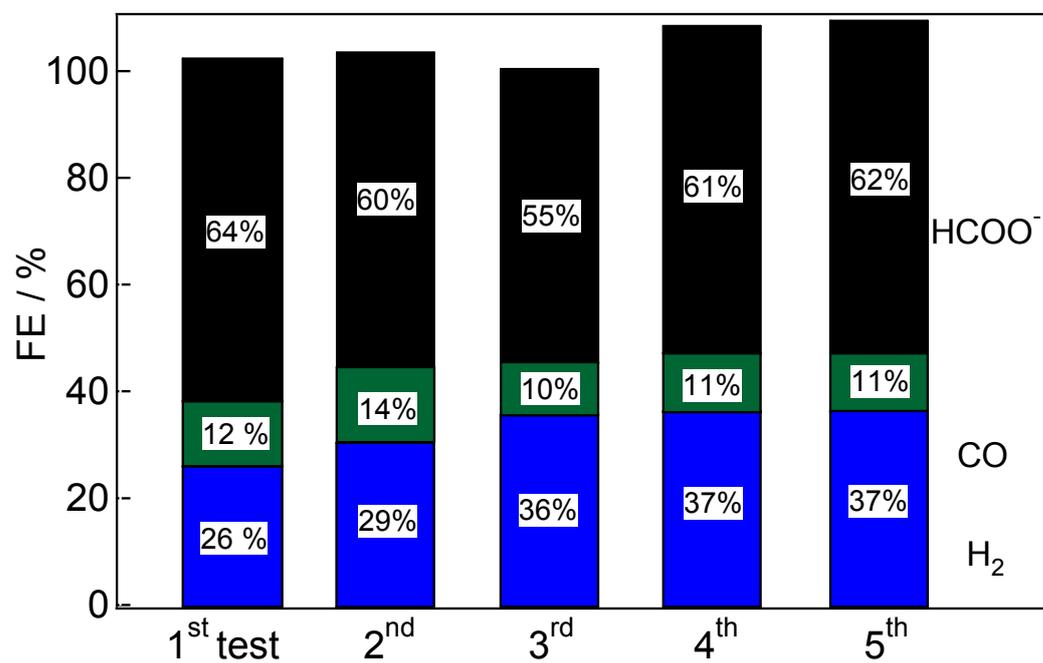
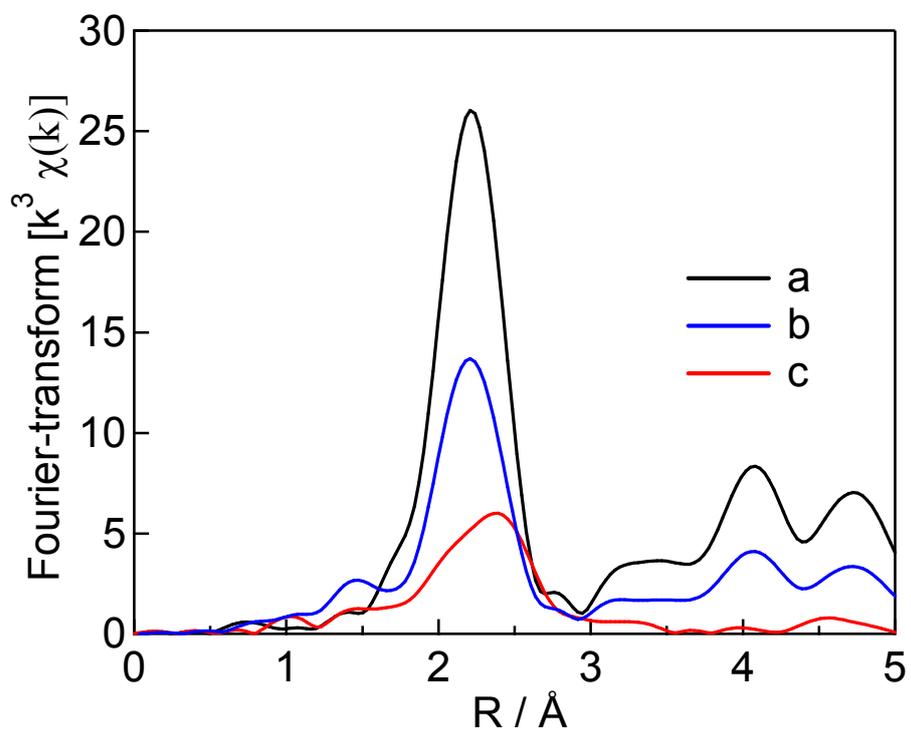


Figure S7 Stability test in the faradaic efficiencies for HCOO<sup>-</sup>, CO, and H<sub>2</sub> produced over Cu<sub>6</sub>Sn<sub>5</sub> NP/CB at -0.6 V over five cycles.



**Figure S8** The  $k^3$ -weighted Fourier-transform from Cu K-edge EXAFS spectra for (a) Cu foil, (b) Cu NPs/CB and (c)  $\text{Cu}_6\text{Sn}_5$  NPs/CB.

**Table S2** Summarized bond type, and distance between the nearest neighbors (R) estimated from the Cu K EXAFS analysis.

	Bond	R (ref.) / Å	R (expt.) / Å	R-factor <sup>a</sup>
Cu foil	Cu- Cu	2.56	2.54	0.0057
Cu <sub>6</sub> Sn <sub>5</sub> NPs/CB	Cu – Cu	2.56	2.49	0.0076
	Cu – Cu	2.61	2.53	
	Cu – Sn	2.69	2.55	
	Cu – Sn	2.74	2.73	
	Cu – Sn	2.82	2.68	
Cu NPs/CB (Cu metal)	Cu – Cu	2.56	2.53	0.059 <sup>b</sup>
	Cu – Cu	2.56	2.54	
Cu NPs/CB (Cu metal and oxide)	Cu – O	1.96	1.86	0.0074 <sup>c</sup>
	Cu – Cu (oxide)	2.94	2.98	

a, The R-factor represents the quality of fitting. b was fitted using Cu metal. c was fitted using Cu metal and Cu oxide.